

## Final Product Change Notification Update

202309003F01U01 : Introduction of Optical Shrink Quad Source Versions of SO-package TJA1021 Product

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 21, 2024 Effective date: May 21, 2024

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to view this notification online

#### **Management summary**

NXP Product Line In-Vehicle Networking (PL IVN) is introducing optical shrink Quad Source versions of SO-package product TJA1021.

### Change Category

[ ]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[ ]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[X]Wafer Fab Location	[X]Assembly Location	[]Packing/Shipping/Labeling	[X]Test Location	[ ]Electrical spec./Test coverage

[]Firmware [X]Other: Optical shrink

# PCN Overview Description

For the PL IVN SO-package LIN product TJA1021, optical shrink Quad Source product versions will be introduced. The Bill-of-Material (BoM) of those new shrink product versions will be using copper (Cu) bondwire, with the associated mold compound and die attach. The new product versions are introduced as Quad Source, i.e. using two front-end diffusion waferfabs and two back-end assembly and final test sites.

This change does not affect the currently released NXP 12NC product part numbers for TJA1021. New 12NCs have been created to make use of the optical shrink Quad Source.

In the attachment to this Product Change Notification (PCN) details of the changes involved are given, as well as three additional documents:

- The AEC-Q100 qualification results for the release

- The applicable ZVEI Delta Qualification Matrix (DeQuMa), both in zipped excel and pdf format

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents. Attached to this e-mail is an excel file with two sheets. One contains the sale history for your affected part numbers, the other the product change list. In both sheets reference is

made to new part number, orderable part number and NXP 12NC code. In case you want to make use of the optical shrink Quad Source you need to order this new part number.

Reason

These changes will help to continue NXP's Global Business Continuity Management process to establish an industrial base that is agile, robust and can reliably service the long term forecasted market growth of IVN products.

Identification of Affected Products Top Side Marking In the attachment to this PCN it is shown how the product name and the marking changes.

### **Product Availability**

Sample Information Samples are available upon request Production Planned first shipment May 21, 2024 Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on specification, form, fit, function(ality), performance, reliability or quality **Data Sheet Revision** No impact to existing datasheet **Disposition of Old Products** Existing inventory will be shipped until depleted **Additional information** 

Self qualification:<u>view online</u> Additional documents: <u>view online</u> **Timing and Logistics** 

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 22, 2024.

## Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files'.

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

In the NXP e-PCN system on the tab 'Products' you can see a list of your affected part numbers. **Update Information** 

The following updates have been made to documents attached to this PCN (see instructions below under heading 'Remarks' on how to obtain these documents) :

- Improved PCN attachment, with more (clear) description of changes
- Typos corrected in reliability qualification report
- Updated ZVEI Delta Qualification Matrix (DeQuMa)

This is purely a documentation update/improvement, there's no further change to the product.

### **Related Notification**

Notification			Title
2023020051	Feb 17, 2023	Mar 17, 2023	TJA1021 Datasheet Update
202309003A	Nov 02, 2023		Introduction of Multi-Source Optical Shrink Versions of Various CAN/LIN Products
• • •			

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Kees van Hasselt	
Position	Quality Account Manager	
e-mail address	ivn.customer.service@nxp.com	

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

#### NXP Quality Management Team.

#### **About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2024 NXP Semiconductors. All rights reserved.